ON Semiconductor®

Final Product/Process Change Notification

Document # : FPCN22788X
Issue Date: 19 July 2019

Title of Change:	Qualify a schottky die (DTSR1030P) as alternative die in FDFS2P106A
Proposed first ship date:	26 October 2019
Contact information:	Contact your local ON Semiconductor Sales Office or <Jinman.Song@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Lake.Wang@onsemi.com>
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>
Change Part Identification:	Qualify a schottky die (DTSR1030P) as alternative die in FDFS2P106A. Customer may receive the FDFS2P106A parts with die from month of October 2019 onwards once FPCN expire.
Change Category:	☐ Wafer Fab Change ☑ Assembly Change ☐ Test Change ☐ Other ________

Change Sub-Category(s):

☐ Manufacturing Site Addition
☐ Manufacturing Site Transfer
☐ Manufacturing Process Change

☑ Material Change
☐ Product specific change

☐ Datasheet/Product Doc change
☐ Shipping/Packaging/Marking
☐ Other: ________________

Sites Affected:	ON Semiconductor Sites: None	External Foundry/Subcon Sites: Gem (Shanghai)

Description and Purpose:

This Notification announces to customers ON Semiconductor's plans to change the schottky die in FDFS2P106A from SIBA-TNVS-WDQ to DTSR1030P. Except die change, no any changes on the BOM, process flow and package, etc. Qualification tests are designed to show that the reliability of the devices with new die will continue to meet or exceed ON Semiconductor standards.

	Before Change Description	After Change Description
Die	SIBA-TNVS-WDQ	DTSR1030P

There is no product marking change as a result of this change.

Reliability Data Summary:

QV DEVICE NAME : FDFS2P106A
RMS: U56130, U60466
PACKAGE: SOIC-8

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta = 150°C , 100% of rated BV for Schottky diode	1008 hrs	0/231
HTSL	JESD22-A103	Ta= 150°C	1008hrs	0/231
PC	J-STD-020 JESD-A113	MSL1 @ 260°C		
TC-PC	JESD22-A104	Ta = -65°C to +150°C	500 cyc	0/231
H3TRB-PC	JESD22-A101	85°C, 85% RH, 80% rated or 100V max	1008 hrs	0/231
uHAST-PC	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231

Electrical Characteristic Summary:

Electrical characteristics are not impacted

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
FDFS2P106A	FDFS2P106A